CD74HC390、CDx4HCT390 高速 CMOS 逻辑双路十进制纹波计数器

1 特性

- 2 个 BCD 十进制或二五混合进制计数器
- 该器件可配置为除以 2、除以 4、除以 5、除以 10、除以 20、除以 25、除以 50、除以 100 模式
- 2 个控制器重置输入，可分别对每个十进制计数器清零
- 扇出（在温度范围内）
  - 标准输出：10 个 LSTTL 负载
  - 总线驱动器输出：15 个 LSTTL 负载
- 宽工作温度范围：-55°C 至 125°C
- 平衡的传播延迟及转换时间
- 与 LSTTL 逻辑 IC 相比，功耗显著降低
- HC 类型
  - 工作电压为 2V 至 6V
  - 高抗噪性：当 V_{CC} = 5V 时，N_{IL} = 30%，N_{IH} = V_{CC} 的 30%
- HCT 类型
  - 工作电压为 4.5V 至 5.5V
  - 直接 LSTTL 输入逻辑兼容性，V_{IL} = 0.8V（最大值），V_{IH} = 2V（最小值）
  - CMOS 输入兼容性，当电压为 V_{OL}、V_{OH} 时，I_I ≤ 1µA

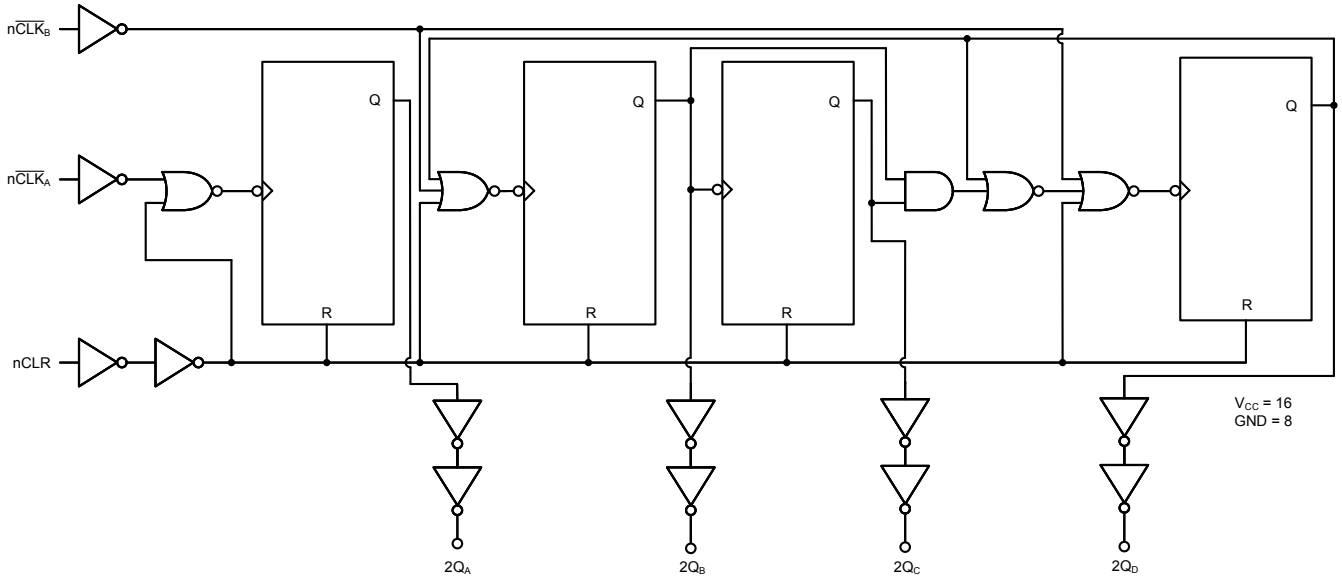
2 说明

SN74HC390 和‘HCT390 器件包含 2 个独立 4 位十进制纹波计数器，下降沿通过异步清零计时。每个计数器均分为两部分，即除以 2 计数器和除以 5 计数器，每一部分都具有独立的时钟输入。这样，就可以灵活地配置器件。

器件信息

器件型号	封装(1)	封装尺寸（标称值）
CD54HCT390F3A	陶瓷双列直插封装 (CDIP) (16)	24.38mm × 6.92mm
CD74HC390M	SOIC (16)	9.90mm × 3.90mm
CD74HCT390M	SOIC (16)	9.90mm × 3.90mm
CD74HC390E	PDIP (16)	19.31mm × 6.35mm
CD74HCT390E	PDIP (16)	19.31mm × 6.35mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



功能方框图

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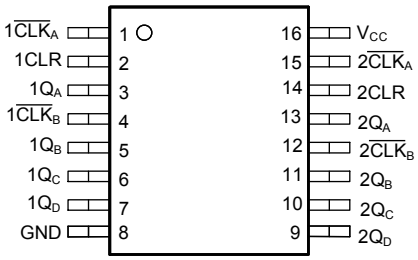
3 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision D (November 2021) to Revision E (April 2022)	Page
• Corrected table 7-3, Q_C value 6 from H to L	10

Changes from Revision C (September 1997) to Revision D (November 2021)	Page
• 更新了整个文档中的编号、格式、表格、图和交叉参考，以反映现代数据表标准	1
• 更新了引脚名称，以符合现行的 TI 命名规则 1$\overline{CP0}$ 现改为 1$\overline{CLK}_A$；1MR 现改为 1CLR；1Q_0 现改为 1Q_A；1$\overline{CP1}$ 现改为 1$\overline{CLK}_B$；1Q_1 现改为 1Q_B；1Q_2 现改为 1Q_C；1Q_3 现改为 1Q_D；2Q_3 现改为 2Q_D；2Q_2 现改为 2Q_C；2Q_1 现改为 2Q_B；2$\overline{CP1}$ 现改为 2$\overline{CLK}_B$；2Q_0 现改为 2Q_A；2MR 现改为 2CLR；2$\overline{CP0}$ 现改为 2$\overline{CLK}_A$	1

4 Pin Configuration and Functions



J, N or D Package
16-Pin CDIP, PDIP, or SOIC
Top View

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	7	V
I_{IK}	Input diode current(2)	(V_I < 0 or V_I > V_{CC})		±20	mA
I_{OK}	Output diode current(2)	(V_O < 0 or V_O > V_{CC})		±20	mA
I_O	Output source or sink current per output pin	(V_O = 0 to V_{CC})		±25	mA
	Continuous current through V_{CC} or GND			±50	mA
T_J	Junction temperature			150	°C
T_{stg}	Storage temperature		-65	150	°C
	Lead temperature (Soldering 10s) (SOIC - Lead tips only)			300	°C

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 Recommended Operating Conditions(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range	HC Types	2	6	V
		HCT Types	4.5	5.5	
V_I, V_O	Input or output voltage		0	V_{CC}	V
t_t	Input rise and fall time	2 V		1000	ns
		4.5 V		500	
		6 V		400	
T_A	Temperature range		– 55	125	℃

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report Implications of Slow or Floating SMOS Inputs, literature number SCBA004.

5.3 Thermal Information

THERMAL METRIC		CD74HC390, CD74HCT390		UNIT
		D (SOIC)	N (PDIP)	
		16 PINS	16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance(1)	73	67	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC package thermal metrics* application report.

5.4 Electrical Characteristics

PARAMETER		TEST CONDITIONS(1)	V_{CC} (V)	25℃			-40℃ to 85℃		-55℃ to 125℃		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
V_{IH}	High level input voltage		2	1.5			1.5		1.5		V
			4.5	3.15			3.15		3.15		V
			6	4.2			4.2		4.2		V
V_{IL}	Low level input voltage		2			0.5		0.5		0.5	V
			4.5			1.35		1.35		1.35	V
			6			1.8		1.8		1.8	V
V_{OH}	High level output voltage	I_{OH} = – 20 μA	2	1.9			1.9		1.9		V
		I_{OH} = – 20 μA	4.5	4.4			4.4		4.4		V
		I_{OH} = – 20 μA	6	5.9			5.9		5.9		V
	High level output voltage	I_{OH} = – 4 mA	4.5	3.98			3.84		3.7		V
		I_{OH} = – 5.2 mA	6	5.48			5.34		5.2		V
V_{OL}	Low level output voltage	I_{OL} = 20 μA	2			0.1		0.1		0.1	V
		I_{OL} = 20 μA	4.5			0.1		0.1		0.1	V
		I_{OL} = 20 μA	6			0.1		0.1		0.1	V
	Low level output voltage	I_{OL} = 4 mA	4.5			0.26		0.33		0.4	V
		I_{OL} = 5.2 mA	6			0.26		0.33		0.4	V
I_I	Input leakage current	V_I = V_{CC} or GND	6			±0.1		±1		±1	μA
I_{CC}	Supply current	V_I = V_{CC} or GND	6			8		80		160	μA
HCT TYPES											
V_{IH}	High level input voltage		4.5 to 5.5	2			2		2		V
V_{IL}	Low level input voltage		4.5 to 5.5			0.8		0.8		0.8	V
V_{OH}	High level output voltage	I_{OH} = – 20 μA	4.5	4.4			4.4		4.4		V
	High level output voltage	I_{OH} = – 4 mA	4.5	3.98			3.84		3.7		V
V_{OL}	Low level output voltage	I_{OL} = 20 μA	4.5			0.1		0.1		0.1	V
	Low level output voltage	I_{OL} = 4 mA	4.5			0.26		0.33		0.4	V
I_I	Input leakage current	V_I = V_{CC} or GND	5.5			±0.1		±1		±1	μA
I_{CC}	Supply current	V_I = V_{CC} or GND	5.5			8		80		160	μA
ΔI_{CC} (2)	Additional supply current per input pin	$n\overline{CLK}_A$ inputs held at V_{CC} – 2.1	4.5 to 5.5		100	162		202.5		220.5	μA
		$n\overline{CLK}_B$, CLR inputs held at V_{CC} – 2.1	4.5 to 5.5		100	216		270		294	

(1) V_I = V_{IH} or V_{IL}, unless otherwise noted.
(2) For dual-supply systems theoretical worst case (V_I = 2.4 V, V_{CC} = 5.5 V) specification is 1.8mA.

5.5 Prerequisite for Switching Characteristics

PARAMETER		V_{CC} (V)	25℃	-40℃ to 85℃		-55℃ to 125℃		UNIT
			MIN	MIN	MAX	MIN	MAX	
HC TYPES								
f_{MAX}	Maximum Clock Frequency	2	6	5		4		MHz
		4.5	30	24		20		
		6	35	28		24		
t_W	Clock Pulse Width, $n\overline{CLK}_A$, $n\overline{CLK}_B$	2	80	100		120		ns
		4.5	16	20		24		
		6	14	17		20		
t_{REM}	Reset Removal Time	2	70	90		105		ns
		4.5	14	18		21		
		6	12	15		18		
t_W	Reset Pulse Width	2	50	65		75		ns
		4.5	10	13		15		
		6	9	11		13		
HCT TYPES								
f_{MAX}	Maximum Clock Frequency	4.5	27	22		18		MHz
t_W	Clock Pulse Width, $n\overline{CLK}_A$, $n\overline{CLK}_B$	4.5	19	24		29		ns
t_{REM}	Reset Removal Time	4.5	15	19		22		ns
t_W	Reset Pulse Width	4.5	13	16		20		ns

5.6 Switching Characteristics

Input t_r, t_f = 6 ns. Unless otherwise specified, C_L = 50pF. (see Parameter Measurement Information)

PARAMETER		V_{CC}(V)	25℃		-40℃ to 85℃	-55℃ to 125℃	UNIT
			TYP	MAX	MAX	MAX	
HC TYPES							
t_{pd}	$n\overline{CLK}_A$ to nQ_A	2		175	220	265	ns
		4.5	14[3]	35	44	53	ns
		6		30	37	45	ns
	$n\overline{CLK}_B$ to nQ_B	2		185	230	280	ns
		4.5		37	46	56	ns
		6		31	39	48	ns
	$n\overline{CLK}_B$ to nQ_C	2		245	305	370	ns
		4.5		49	61	74	ns
		6		42	52	63	ns
	$n\overline{CLK}_B$ to nQ_D	2		180	225	270	ns
		4.5	15[3]	36	45	54	ns
		6		31	38	46	ns
	$n\overline{CLK}_A$ to nQ_D	2		365	455	550	ns
		4.5		73	91	110	ns
		6		62	77	94	ns
	CLR to Q_n	2		190	240	285	ns
		4.5	16[3]	38	48	57	ns
		6		32	41	48	ns

5.6 Switching Characteristics (continued)

Input t_r, t_f = 6 ns. Unless otherwise specified, C_L = 50pF. (see Parameter Measurement Information)

PARAMETER		V_{CC}(V)	25℃		-40℃ to 85℃	-55℃ to 125℃	UNIT
			TYP	MAX	MAX	MAX	
t_t	Output Transition Times	2		75	95	110	ns
		4.5		15	19	22	ns
		6		13	16	19	ns
C_{IN}	Input Capacitance			10	10	10	pF
C_{PD}	Power Dissipation Capacitance(1) (2)	5	28(3)				pF
HCT TYPES							
t_{pd}	$n\overline{CLK}_A$ to nQ_A	4.5	17(3)	40	50	60	ns
	$n\overline{CLK}_B$ to nQ_B	4.5		43	51	65	ns
	$n\overline{CLK}_B$ to nQ_C	4.5		55	69	83	ns
	$n\overline{CLK}_B$ to nQ_D	4.5	18(3)	42	53	63	ns
	$n\overline{CLK}_A$ to nQ_C	4.5		84	105	126	ns
	CLR to Q_n	4.5	18(3)	42	53	63	ns
t_t	Output Transition Times	4.5		15	19	22	ns
C_{IN}	Input Capacitance			10(4)	10(4)	10(4)	pF
C_{PD}	Power Dissipation Capacitance(1) (2)	5	32(3)				pF

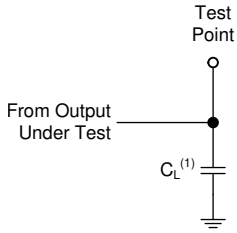
(1) C_{PD} is used to determine the dynamic power consumption, per package.
(2) $P_D = V_{CC}^2 f_i + \Sigma (C_L V_{CC}^2 + f_O)$ where f_i = Input Frequency, f_O = Output Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.
(3) C_L = 15 pF and V_{CC} = 5 V.
(4) C_L = 15 pF

6 Parameter Measurement Information

Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_t < 6 ns.

For clock inputs, f_{max} is measured when the input duty cycle is 50%.

The outputs are measured one at a time with one input transition per measurement.



(1) C_L includes probe and test-fixture capacitance.

图 6-1. Load Circuit for Push-Pull Outputs

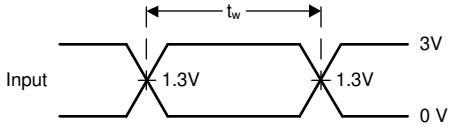


图 6-2. Voltage Waveforms, TTL-Compatible CMOS Inputs Pulse Duration

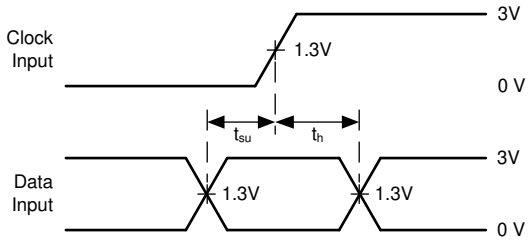
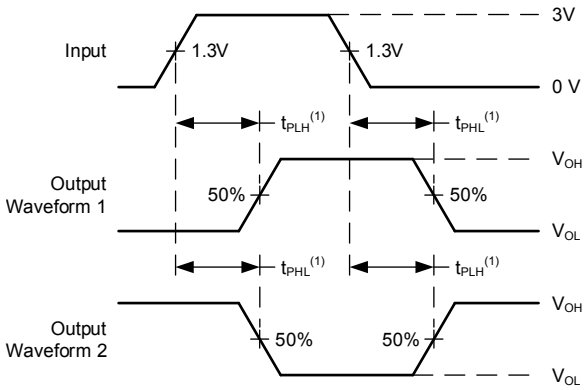


图 6-3. Voltage Waveforms, TTL-Compatible CMOS Inputs Setup and Hold Times



(1) The greater between t_{PLH} and t_{PHL} is the same as t_{pd}.

图 6-4. Voltage Waveforms, TTL-Compatible CMOS Inputs Propagation Delays

7 Detailed Description

7.1 Overview

The CD74HC390 and ’ HCT390 dual 4-bit decade ripple counters are high-speed silicon-gate CMOS devices and are pin compatible with low-power Schottky TTL (LSTTL). These devices are divided into four separately clocked sections. The counters have two divide-by-2 sections and two divide-by-5 sections. These sections are normally used in a BCD decade or bi-quinary configuration, since they share a common controller reset (nCLR). If the two controller reset inputs (1CLR and 2CLR) are used to simultaneously clear all 8 bits of the counter, a number of counting configurations are possible within one package. The separate clock inputs ($n\overline{CLK}_A$ and $n\overline{CLK}_B$) of each section allow ripple counter or frequency division applications of divide-by-2, 4, 5, 10, 20, 25, 50, or 100. Each section is triggered by the High-to-Low transition of the input pulses ($n\overline{CLK}_A$ and $n\overline{CLK}_B$).

For BCD decade operation, the nQ_A output is connected to the $n\overline{CLK}_B$ input of the divide-by-5 section. For bi-quinary decade operation, the nQ_D output is connected to the $n\overline{CLK}_A$ input and nQ_A becomes the decade output.

The controller reset inputs (1CLR and 2CLR) are active-High asynchronous inputs to each decade counter which operates on the portion of the counter identified by the “1” and “2” prefixes in the pin configuration. A High level on the nCLR input overrides the clock and sets the four outputs Low.

7.2 Functional Block Diagram

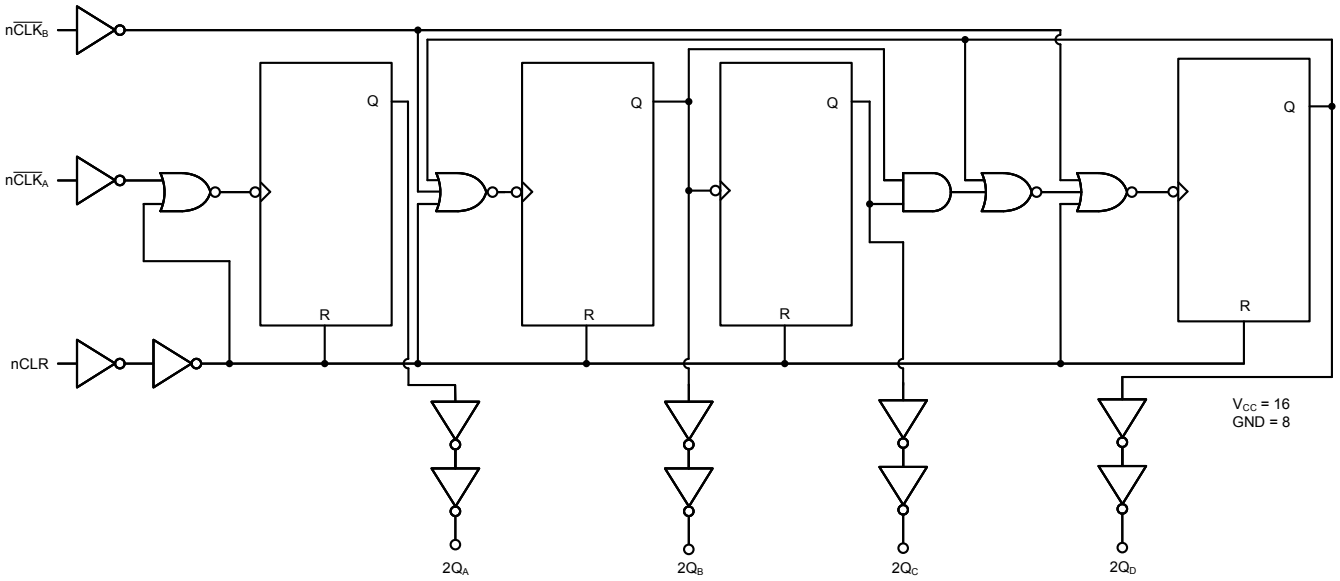


图 7-1. Functional Block Diagram

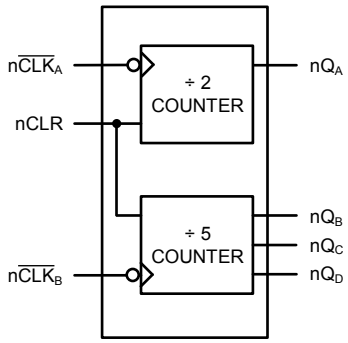


图 7-2. Functional Pinout

7.3 Device Functional Modes

表 7-1. Truth Table(1)

INPUTS		ACTION
$\overline{CLK}$	CLR	
↑	L	No Change
↓	L	Count
X	H	All Qs Low

(1) H = High voltage level.
L = Low voltage level.
X = Dont care.
↑ = Transition from low to high level.
↓ = Transition from high to low.

表 7-2. BCD Count Sequence For ½ the 390(1)

COUNT	OUTPUTS			
	Q_D	Q_C	Q_B	Q_A
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
5	L	H	L	H
6	L	H	H	L
7	L	H	H	H
8	H	L	L	L
9	H	L	L	H

(1) Ouput nQ_A connected to $n\overline{CLK}_B$ with counter input on $n\overline{CLK}_A$.

表 7-3. B-Quinary Count Sequence For ½ the 390(1)

COUNT	OUTPUTS			
	Q_D	Q_C	Q_B	Q_A
0	L	L	L	L
1	L	L	H	L
2	L	H	L	L
3	L	H	H	L
4	H	L	L	L
5	L	L	L	H
6	L	L	H	H
7	L	H	L	H
8	L	H	H	H
9	H	L	L	H

(1) Output nQ_D connected to $n\overline{CLK}_A$ with counter input on $n\overline{CLK}_B$.

8 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1-μF capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1-μF and 1-μF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

9 Layout

9.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC}, whichever makes more sense for the logic function or is more convenient.

10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

10.1 Documentation Support

10.1.1 Related Documentation

10.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 *订阅更新* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

10.3 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

10.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

10.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.6 术语表

TI 术语表	本术语表列出并解释了术语、首字母缩略词和定义。

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9098401MEA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9098401ME A CD54HCT390F3A	Samples
CD54HCT390F3A	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9098401ME A CD54HCT390F3A	Samples
CD74HC390E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC390E	Samples
CD74HC390EE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC390E	Samples
CD74HC390M	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125	HC390M	
CD74HC390M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	-55 to 125	HC390M	Samples
CD74HCT390E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT390E	Samples
CD74HCT390EE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT390E	Samples
CD74HCT390M	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125	HCT390M	
CD74HCT390M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT390M	Samples
CD74HCT390MT	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-55 to 125	HCT390M	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF CD54HCT390, CD74HCT390 :

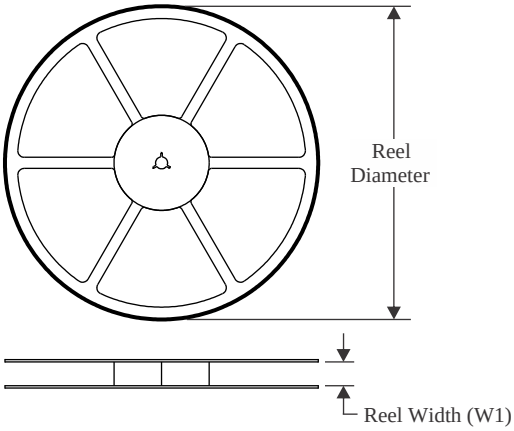
- Catalog : CD74HCT390
- Military : CD54HCT390

NOTE: Qualified Version Definitions:

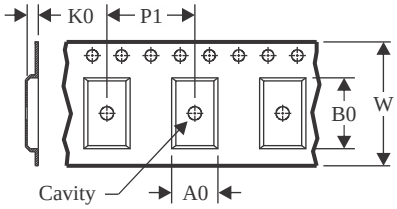
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

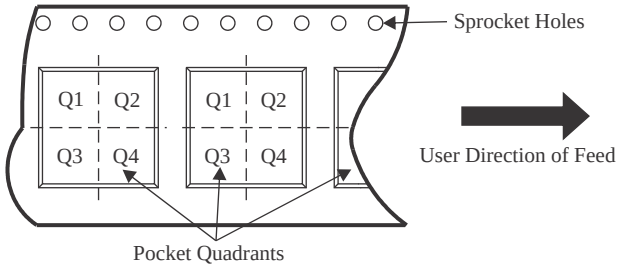


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

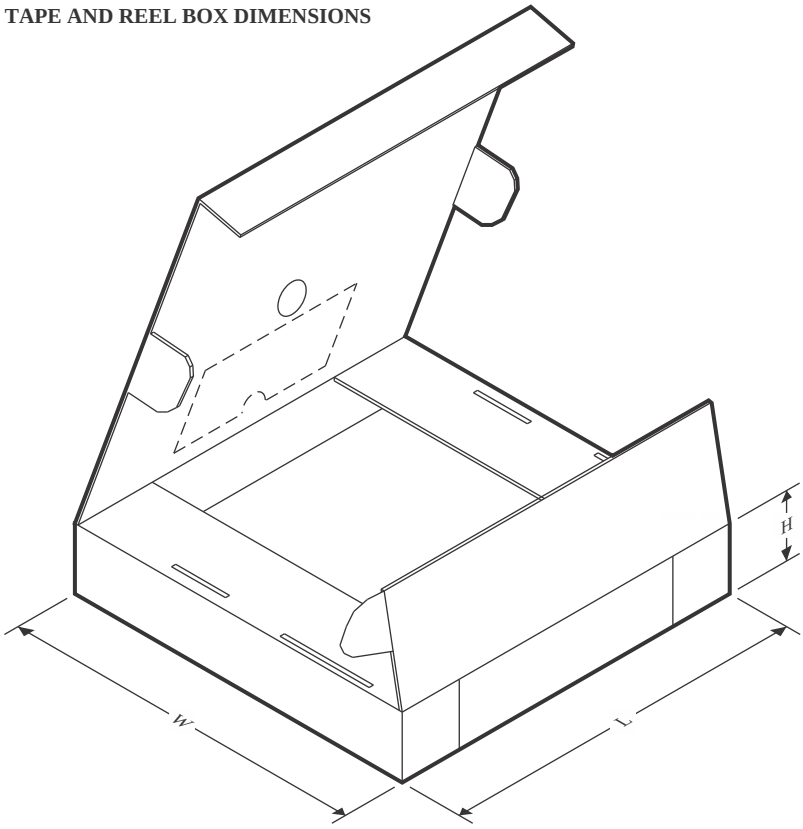
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC390M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HCT390M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

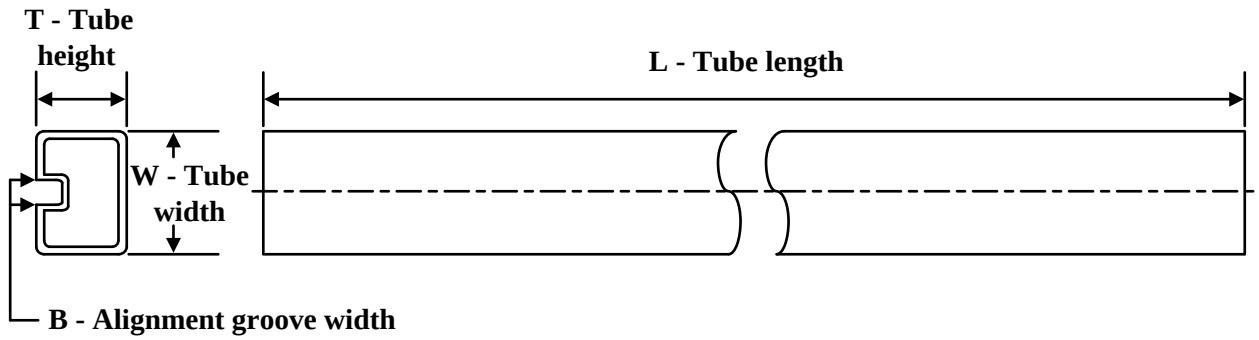
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC390M96	SOIC	D	16	2500	356.0	356.0	35.0
CD74HCT390M96	SOIC	D	16	2500	353.0	353.0	32.0

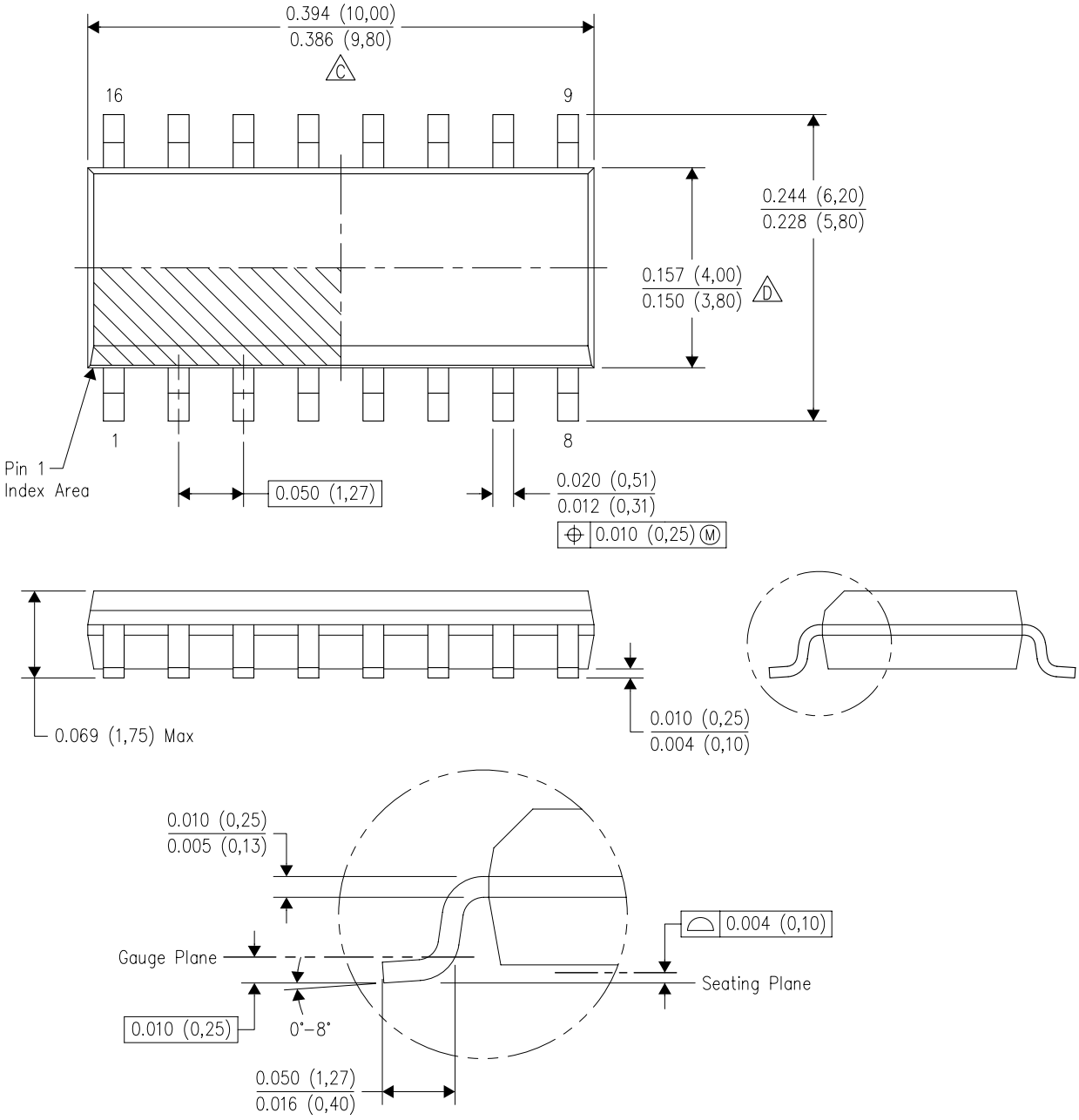
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74HC390E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC390E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC390EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC390EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT390E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT390E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT390EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT390EE4	N	PDIP	16	25	506	13.97	11230	4.32

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

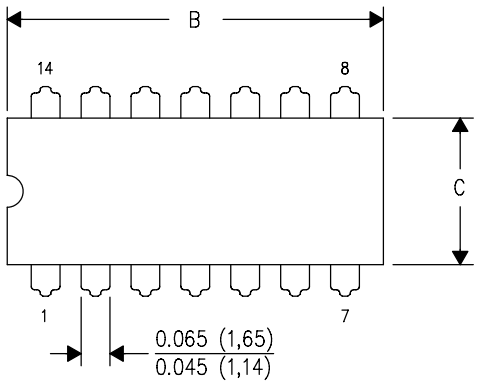


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

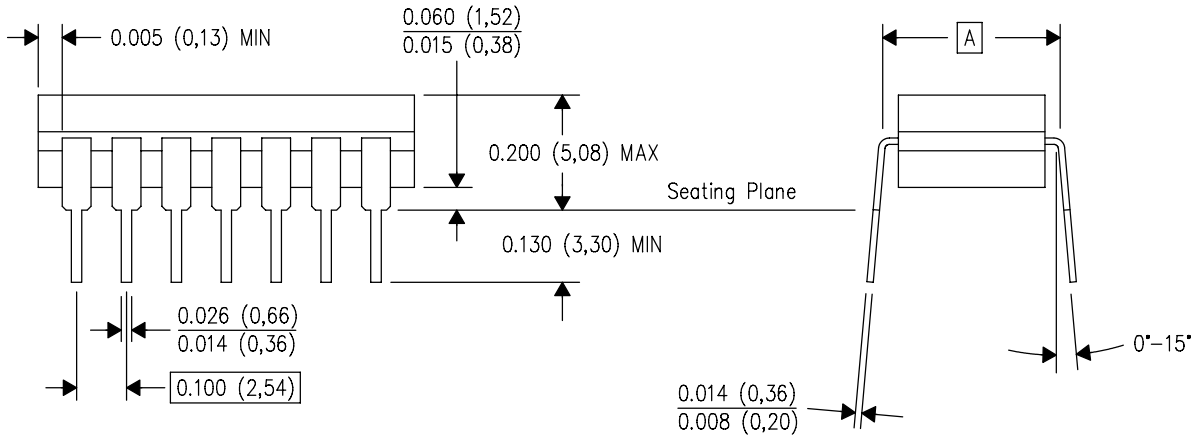
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



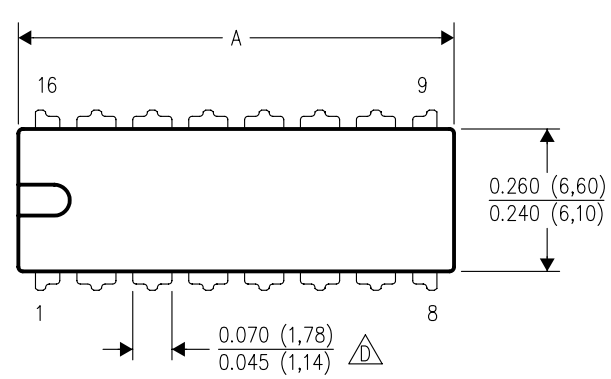
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

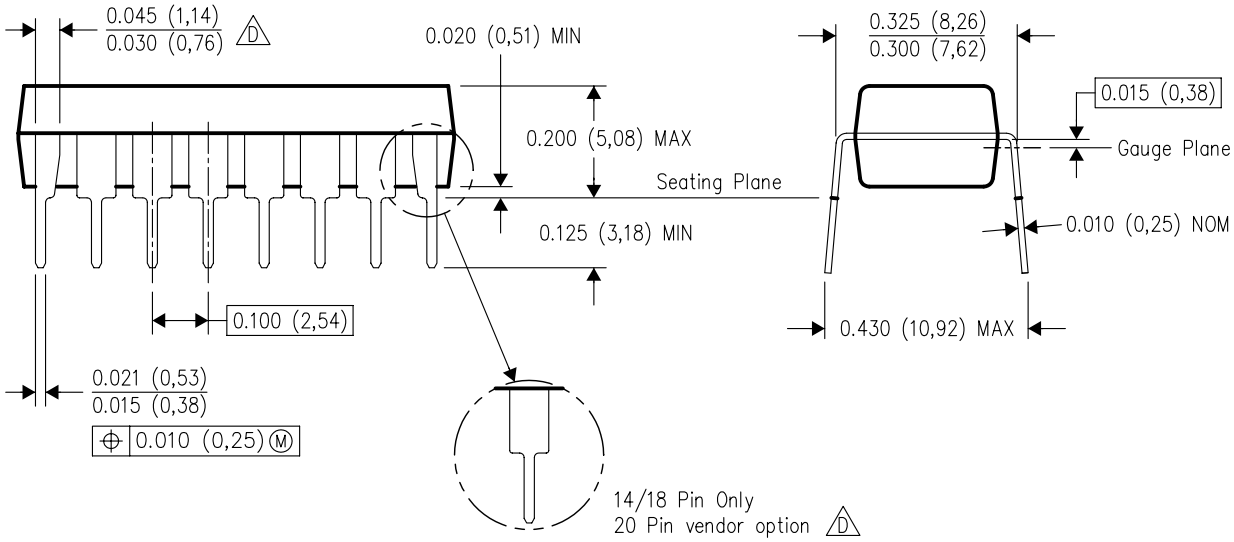
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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